



## **Case Study: Product Development Heat Exchange Plate**

A specialty semi-conductor (fusion) testing manufacturer required a high efficiency PCB liquid based heat exchanger. A concept of two formed copper plates soldered together existed, with no known manufacturing process available allowing for viable commercialization.

PEKO developed a complete commercialized product design and production process including; product design package, press tooling, solder dispense, solder fixturing, testing, and final flushing. Critical parameter analysis coupled with multiple design of experiment (DOE) efforts increased yields to cost efficient levels. Through this process PEKO engineered success for the client.

